IN THE CLAIMS:

Please cancel claims 1 and 13 without prejudice.

Please amend claims 2, 4-6, 9, 14-16, and 19 as follows:

1. (Canceled)

2. (Currently Amended) The injection mold according to claim [[1]] 16, wherein the complementary channel extends from the injection channel.

3. (Original) The injection mold according to claim 2, wherein the complementary channel connects two injection channels that are connected to the transfer chamber, and extends some distance from the transfer chamber.

4. (Currently Amended) The injection mold according to claim [[1]] 16, wherein the complementary channel connects two injection channels, the two injection channels being connected to the transfer chamber.

5. (Currently Amended) The injection mold according to claim [[1]] 19, wherein the at least one blind complementary channel also directly communicates with the transfer chamber.

6. (Currently Amended) The injection mold according to claim [[1]] 19, wherein the at least one blind complementary channel also directly communicates with the injection cavity.

7. (Previously Presented) An injection mold for injection molding an encapsulation material to encapsulate at least one integrated circuit chip, said injection mold comprising:

at least two parts that define at least one injection circuit, the injection circuit including:

at least one injection cavity for housing the chip;

at least one transfer chamber from which the encapsulation material is injected; and

at least one injection channel connecting the transfer chamber to the injection cavity;

at least one blind complementary channel communicating with the injection circuit, the blind complementary channel being formed between the two parts of the mold and forming at least one appendage of encapsulation material that is connected to the encapsulation material that fills the injection circuit; and

an insert having one face that partly constitutes the wall of the injection cavity,

wherein the complementary channel extends around the insert so as to form an annular space communicating with the injection cavity.

8. (Original) The injection mold according to claim 7, wherein a part of the annular space that is remote from the cavity is enlarged.

9. (Currently Amended) A method for injection molding an encapsulation material to encapsulate at least one integrated circuit chip, said method comprising the steps of:

placing a leadframe supporting the chip in an injection mold having at least one injection circuit formed between two parts of the mold and in at least one of the parts, the injection circuit including at least one injection cavity for housing the chip, at least one transfer chamber from which liquid encapsulation material is injected, and at least one injection channel formed in a parting line or plane of the mold and connecting the transfer chamber to the injection cavity;

injecting the liquid encapsulation material into the injection cavity via the injection channel so that the liquid encapsulation material fills the cavity and at least one blind complementary channel of the injection mold, the blind complementary channel formed between the two parts of the mold and in at least one of the parts, and directly communicating with the injection channel at some distance from the injection cavity and the transfer chamber, and the at least one blind complementary channel being not directly connected to any injection cavity of the injection circuit so as to not directly communicate with any injection cavity of the injection circuit; and

hardening the liquid encapsulation material so as to form a molded part that includes an integrated circuit package corresponding to the injection cavity and at least one complementary branch of encapsulation material corresponding to the at least one blind complementary channel, the complementary branch of encapsulation material being connected to the hardened encapsulation material filling the injection channel so that if flash was formed between the two parts of the mold in its parting line or plane, then after demolding such flash stays attached to at least the encapsulation material that filled the injection channel and the complementary branch of encapsulation material.

10. (Original) The method according to claim 9, wherein the complementary channel extends from the injection channel.

11. (Previously Presented) The method according to claim 9, wherein the complementary channel connects two injection channels of the mold, the two injection channels being connected to the same transfer chamber.

12. (Previously Presented) The method according to claim 9, wherein the complementary channel also directly communicates with the transfer chamber.

13. (Canceled)

14. (Currently Amended) The injection mold according to claim [[1]] 16, wherein the blind complementary channel is a means for forming complementary attachment means for flash that is formed during injection molding.

15. (Currently Amended) The injection mold according to claim [[1]] 16, wherein the complementary channel connects two injection channels that are connected to the same transfer chamber.

16. (Currently Amended) ~~The~~ An injection mold ~~according to claim 1,~~ for injection molding an encapsulation material to encapsulate at least one integrated circuit chip, said injection mold comprising:

at least two parts that define at least one injection circuit formed between the two parts and in at least one of the parts, the injection circuit including:

at least one injection cavity for housing the chip;

at least one transfer chamber from which the encapsulation material is injected; and

at least one injection channel formed in a parting line or plane of the mold, the at least one injection channel connecting the transfer chamber to the injection cavity; and

at least one blind complementary channel formed between the two parts of the mold and in at least one of the parts, the blind complementary channel directly communicating with the injection channel at some distance from the injection cavity and the transfer chamber such that the blind complementary channel causes the formation of at least one appendage of encapsulation material that is connected to the encapsulation material that fills the injection channel, so that if during injection molding flash is formed between the two parts of the mold in its parting line or plane, then after demolding such flash stays attached to at least the encapsulation material that filled the injection channel and the blind complementary channel,

wherein the at least one blind complementary channel is not directly connected to any injection cavity of the injection circuit so as to not directly communicate with any injection cavity of the injection circuit.

17. (Previously Presented) The injection mold according to claim 16, wherein the at least one blind complementary channel is not directly connected to any transfer chamber of the injection circuit so as to not directly communicate with any transfer chamber of the injection circuit.

18. (Previously Presented) The injection mold according to claim 17, wherein the blind complementary channel is a means for forming complementary attachment means for flash that is formed during injection molding, and has no function in injecting the encapsulation material into the injection cavity to encapsulate the integrated circuit chip.

19. (Currently Amended) ~~The~~ An injection mold ~~according to claim 1,~~ for injection molding an encapsulation material to encapsulate at least one integrated circuit chip, said injection mold comprising:

at least two parts that define at least one injection circuit formed between the two parts and in at least one of the parts, the injection circuit including:

at least one injection cavity for housing the chip;

at least one transfer chamber from which the encapsulation material is injected; and

at least one injection channel formed in a parting line or plane of the mold, the at least one injection channel connecting the transfer chamber to the injection cavity; and

at least one blind complementary channel formed between the two parts of the mold and in at least one of the parts, the blind complementary channel directly communicating with the injection channel at some distance from the injection cavity and the transfer chamber such that the blind complementary channel causes the formation of at least one appendage of encapsulation material that is connected to the encapsulation material that fills the injection channel, so that if during injection molding flash is formed between the two parts of the mold in its parting line or plane, then after demolding such flash stays attached to at least the encapsulation material that filled the injection channel and the blind complementary channel,

wherein the at least one blind complementary channel includes a first blind complementary channel, a second blind complementary channel, and a third blind complementary channel, and

the third blind complementary channel connects the first and second blind complementary channels.

20. (Previously Presented) The injection mold according to claim 19, wherein the first and second blind complementary channels each connect two injection channels of the mold.